Edgebanding
Technical Training
Edge Banding
Roller Coater

Adhesive being applied to the edge of the board
Edge Banding
Roller Coater - coding

Application roller coding

1.3mm
Edge Banding
Roller Coater – guide plate setting

Set the guide plate so that the roller is 0.1 – 0.2mm from the board edge

Benefits:
• Even adhesive coating on the edging
• Improved adhesive wetting out on the edging
• Improved bond line
• Higher bond strength
• Reduced fibre contamination on the roller coater
• Reduced contamination in the glue pot
• Reduced damage to the board edge
• Increased heat resistance
• Increased water resistance
Edge Banding
Roller Coater – guide plate setting

Guide plate setting on the application roller

0,1 – 0,2 mm
Edge Banding
Roller Coater – guide plate setting

Guide Plate
Edge Banding
Roller Coater – guide plate setting

Guide plate adjustment screws
Edge Banding
Roller Coater – guide plate setting

Application roller running directly on the board
Edge Banding
Roller Coater – guide plate setting

Roller coater set with direct contact to the board giving an uneven coating. (magnified x 40)
Edge Banding
Roller Coater – guide plate setting

Application roller set correctly using the guide plate
Edge Banding
Temperature control

Board = Room temperature

Adhesive = application temp.

Edging = Room temperature
Edge Banding
Temperature control

Measure both panel and edge temperature

Temperature setting (melting equipment) in line with recommendation of hotmelt supplier (please check Technical Data Sheet)
Edge Banding
Temperature control

Measure correct temperature on roller and compare it with figure shown on display. Adjust if required.

Measure adhesive temperature (contact) on the board before the edging is applied.
Edge Banding
Pressure roller

Check correct pressure on display.

Additionally, check correct pressure directly on roller.
# Edge Banding
## Pressure roller - settings

<table>
<thead>
<tr>
<th>Edging Material</th>
<th>Main Pressure Roller</th>
<th>Small Pressure Roller</th>
</tr>
</thead>
<tbody>
<tr>
<td>Thin edging</td>
<td>2.5 bar</td>
<td>3 bar</td>
</tr>
<tr>
<td>Thick edging</td>
<td>3 bis 4 bar</td>
<td>3 bar</td>
</tr>
<tr>
<td>Solid Wood</td>
<td>&lt; 1 bar</td>
<td>3 bar</td>
</tr>
</tbody>
</table>
Store adhesive in a dry, and dust free environment.

Set the correct application temperature of the adhesive.

Adhesive application weight has to be set correctly, with an even coating across the edge, and with the correct guide plate setting.

Set the pressure roller to the correct setting according to the edging being run.

Ensure the edge preparation of the board is a 90 degrees.

Both board and edge temperature have a minimum of 18 °C.

Ensure correct extraction around the roller coater.

Avoid dust contamination in the area of adhesive application.
Edge Banding
Fault Finding
Edge Banding
Transparent edge fault finding

Smooth hotmelt coating above, no hotmelt below or vice versa

Panel not right angled.

Open pores in middle layer of panel

Hotmelt amount too low

Smooth hotmelt coating

Hotmelt application ok

Thursday, 1 August 13
**Edge Banding**

Transparent edge fault finding

**Hotmelt shows pattern of roller**

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Hotmelt too cold or Chipboard too cold or the pressure roller set too low

**Pattern of roller above, smooth hotmelt coating below, or vice versa**

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Chipboard not correctly angled or the pressure roller not correctly angled
Thank You